AMENDMENTS TO THE CLAIMS

1-10. (Canceled)

11. (Previously presented) An imaging system, comprising:

a transmitting system for transmitting an image including an image source, said transmitting system being arranged to transmit the entire image simultaneously onto each of a plurality of imaging devices;

wherein each of said plurality of imaging devices includes a semiconductor device including an array of photosensitive elements, each semiconductor device being mounted on a respective frame, each of said frames having a support structure, each of said support structures comprising a cavity defined by side walls and a closed bottom, each of said semiconductor devices receiving said image and generating corresponding signals; and

wherein each said frame, support structure, and respective semiconductor device is encapsulated in a transparent material of a respective package for protecting and supporting each said semiconductor device, said transparent material being fully contained by said side walls and closed bottom and including injection molded resin for allowing the image from said image source to pass to said semiconductor devices, said transparent material of at least one of said packages having a color different from remaining packages.

12. (Original) The system of claim 11, wherein said image source includes a lens.

13. (Currently amended) The system of claim 11 wherein each of said ~~semiconductor~~ plurality of imaging devices further includes a color filter, wherein said respective color filters are complementary ~~color filters~~.

14. (Previously presented) The system of claim 13, wherein said complementary color filters are molded into said packages.

15. (Previously presented) The system of claim 13, wherein said packages include red, green and blue filters.

16. (Previously presented) The system of claim 13, wherein said packages include cyan, magenta and yellow filters.

Claims 17-27. (Canceled)

28. (Currently amended) An imaging device, comprising:

a rigid housing having a cavity defined by side walls and a closed bottom;

a semiconductor imaging chip located within said cavity of said housing, said semiconductor imaging chip including an array of photosensitive elements configured to receive an image and generate corresponding signals, said photosensitive elements being covered by a transparent cover;

said semiconductor imaging chip being encapsulated in a transparent material, wherein said transparent material is disposed within said cavity, ~~and~~ is fully contained by said side walls and closed bottom of said housing, and has an uppermost surface substantially planar to an uppermost surface of said sidewalls of said housing; and

an optical light transmitting device configured to transmit light between an image and said photosensitive elements.

29. (Previously presented) The device of claim 28, wherein said transparent cover includes a color filter.

Claim 30. (Canceled)

31. (Previously presented) The imaging device of claim 28, wherein said housing is formed of molded plastic.

32. (Canceled)

33. (Previously presented) The imaging device of claim 28, wherein said housing is formed of a ceramic material.

34-35. (Canceled)

36. (New) An imaging system, comprising:

a plurality of imaging devices configured to simultaneously receive an entire image, wherein each imaging device comprises a semiconductor device that is mounted on a respective frame,

wherein each of said semiconductor devices includes an array of photosensitive elements configured to receive said image,

wherein each of said frames has a support structure comprising a cavity defined by side walls and a closed bottom,

wherein each of said semiconductor devices is encapsulated in a transparent material for protecting and supporting said semiconductor device,

wherein said transparent material is fully contained by said side walls and closed bottom and comprises an injection molded resin that allows said image to pass to said semiconductor device, and

wherein said transparent material encapsulating at least one of said semiconductor devices has a color different from that of said transparent material encapsulating the remaining semiconductor devices.

37. (New) The system of claim 36 wherein each of said plurality of imaging devices further includes a color filter, wherein said respective color filters are complementary.

38. (New) The system of claim 37, wherein said complementary color filters are molded into said transparent material.

39. (New) The system of claim 37, wherein said complementary color filters include red, green and blue filters.

40. (New) The system of claim 37, wherein said complementary color filters include cyan, magenta and yellow filters.

41. (New) An imaging device, comprising:

a rigid housing having a cavity defined by side walls and a closed bottom;

a semiconductor imaging chip located within said cavity of said housing, said semiconductor imaging chip including an array of photosensitive elements configured to receive an image and generate corresponding signals, said photosensitive elements being covered by a transparent cover;

said semiconductor imaging chip being encapsulated in a transparent material, wherein said transparent material is disposed within said cavity, is fully contained by said side walls and closed bottom of said housing, and has an uppermost surface substantially planar to an uppermost surface of said sidewalls of said housing; and

an optical light transmitting device configured to transmit light from an image to said photosensitive elements.